



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et. al

Serial No.: 10/648,654

Filed: August 26, 2003

For: METHODS FOR STRESS
REDUCTION FEATURE FOR LOC LEAD
FRAME

Confirmation No.: 3870

Examiner: J. Fischer

Group Art Unit: 1733

Attorney Docket No.: 2269-2739.6US
(95-1011.05/US)

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AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Title begin on page 3 of this paper;

Amendments to the Specification begin on page 4 of this paper;

Amendments to the Claims are set forth in the listing of the claims that begins on page 7 of this paper;

Corrections to the Drawings are summarized on page 17 of this paper, with a replacement sheet and an annotated sheet showing the corrections enclosed herewith; and

Remarks start at page 18 of this paper.

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

**METHODS-ASSEMBLY METHOD FOR SEMICONDUCTOR DIE AND STRESS
REDUCTION FEATURE FOR LOC LEAD FRAME**